



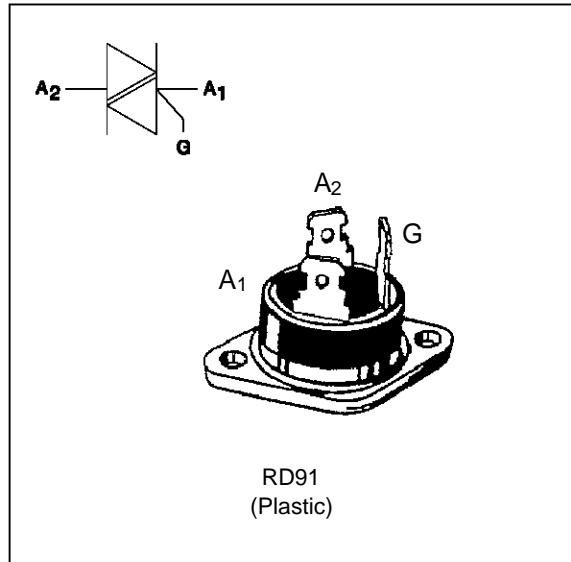
## STANDARD TRIACS

### FEATURES

- HIGH SURGE CURRENT CAPABILITY
- COMMUTATION :  $(dV/dt)c > 10V/\mu s$
- BTA Family :  
INSULATING VOLTAGE = 2500V(RMS)  
(UL RECOGNIZED : E81734)

### DESCRIPTION

The BTA25 A/B triac family are high performance glass passivated PNPN devices.  
These parts are suitable for general purpose applications where high surge current capability is required. Application such as phase control and static switching on inductive or resistive load.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I <sub>T</sub> (RMS)	RMS on-state current (360° conduction angle)	30	A
I <sub>TSM</sub>	Non repetitive surge peak on-state current ( T <sub>j</sub> initial = 25°C )	tp = 8.3 ms	260
		tp = 10 ms	250
I <sub>2t</sub>	I <sub>2t</sub> value	312.5	A <sub>2s</sub>
dI/dt	Critical rate of rise of on-state current Gate supply : I <sub>G</sub> = 500mA diG/dt = 1A/μs	Repetitive F = 50 Hz	10
		Non Repetitive	50
T <sub>stg</sub> T <sub>j</sub>	Storage and operating junction temperature range	- 40 to + 150 - 40 to + 125	°C °C
T <sub>I</sub>	Maximum lead temperature for soldering during 10 s at 4.5 mm from case	260	°C

Symbol	Parameter	BTA25... A/B				Unit
		400	600	700	800	
V <sub>DRM</sub> V <sub>RRM</sub>	Repetitive peak off-state voltage T <sub>j</sub> = 125 °C	400	600	700	800	V

**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
R <sub>th</sub> (j-c) DC	Junction to case for DC	1.5	°C/W
R <sub>th</sub> (j-c) AC	Junction to case for 360° conduction angle (F= 50 Hz)	1.1	°C/W

**GATE CHARACTERISTICS (maximum values)**

P<sub>G</sub> (AV) = 1W    P<sub>GM</sub> = 40W (tp = 20 μs)    I<sub>GM</sub> = 8A (tp = 20 μs)    V<sub>GM</sub> = 16V (tp = 20 μs).

**ELECTRICAL CHARACTERISTICS**

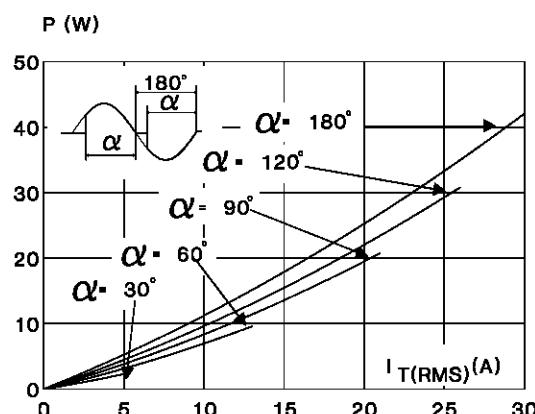
Symbol	Test Conditions	Quadrant	Suffix		Unit
			A	B	
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III	MAX	100
			IV	MAX	50
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III-IV	MAX	150
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> =125°C	I-II-III-IV	MIN	100
t <sub>GT</sub>	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 500mA dI <sub>G</sub> /dt = 3A/μs	T <sub>j</sub> =25°C	I-II-III-IV	TYP	2.5
I <sub>L</sub>	I <sub>G</sub> =1.2 I <sub>GT</sub>	T <sub>j</sub> =25°C	I-III-IV	TYP	70
			II		60
I <sub>H</sub> *	I <sub>T</sub> = 500mA gate open	T <sub>j</sub> =25°C		MAX	200
				MAX	80
V <sub>TM</sub> *	I <sub>TM</sub> = 42A tp= 380μs	T <sub>j</sub> =25°C		MAX	1.8
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>DRM</sub> Rated V <sub>RRM</sub> Rated	T <sub>j</sub> =25°C		MAX	0.01
		T <sub>j</sub> =125°C		MAX	6
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	T <sub>j</sub> =125°C		MIN	250
(dV/dt) <sub>C</sub> *	(dI/dt) <sub>C</sub> = 13.3A/ms	T <sub>j</sub> =125°C		MIN	10
					V/μs

\* For either polarity of electrode A2 voltage with reference to electrode A1.

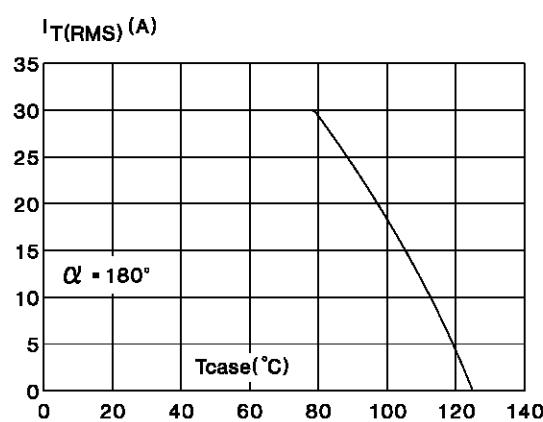
## ORDERING INFORMATION

Package	$I_T(\text{RMS})$	$V_{\text{DRM}} / V_{\text{RRM}}$	Sensitivity Specification	
	A	V	A	B
BTA (Insulated)	30	400	X	X
		600	X	X
		700	X	X
		800	X	X

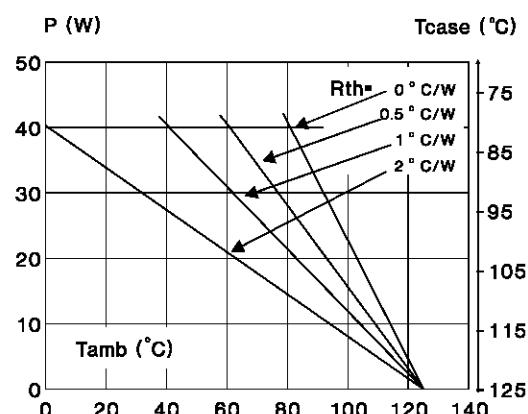
**Fig.1 :** Maximum RMS power dissipation versus RMS on-state current ( $F=50\text{Hz}$ ).  
(Curves are cut off by  $(dI/dt)_c$  limitation)



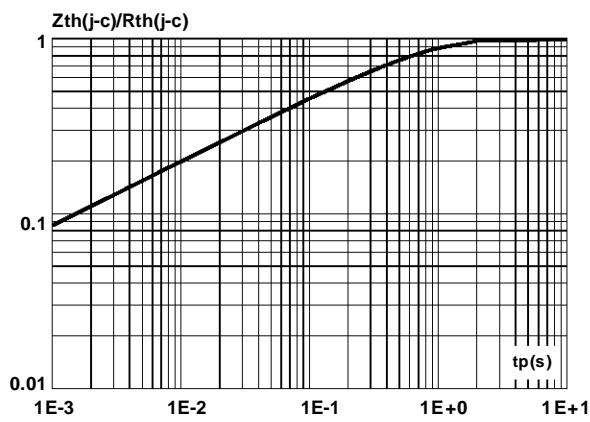
**Fig.3 :** RMS on-state current versus case temperature.



**Fig.2 :** Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{\text{amb}}$  and  $T_{\text{case}}$ ) for different thermal resistances heatsink + contact.

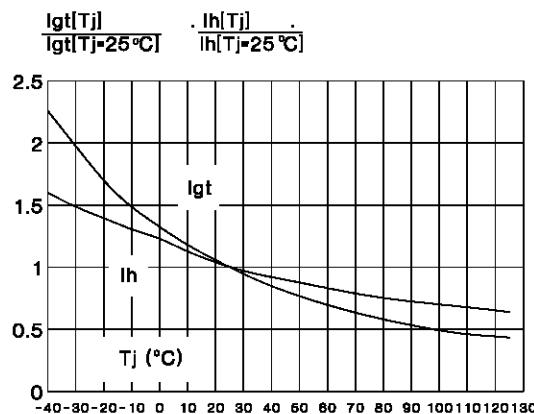


**Fig.4 :** Relative variation of thermal impedance junction to case versus pulse duration.

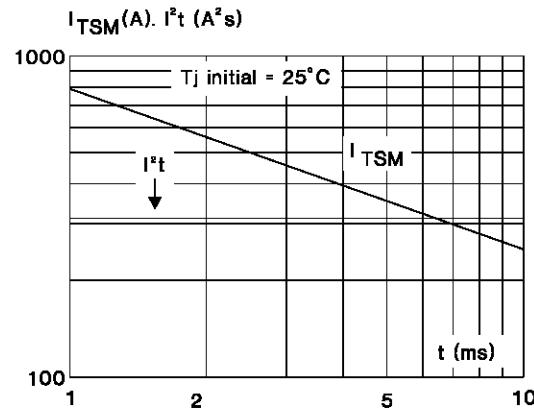


## BTA25 A/B

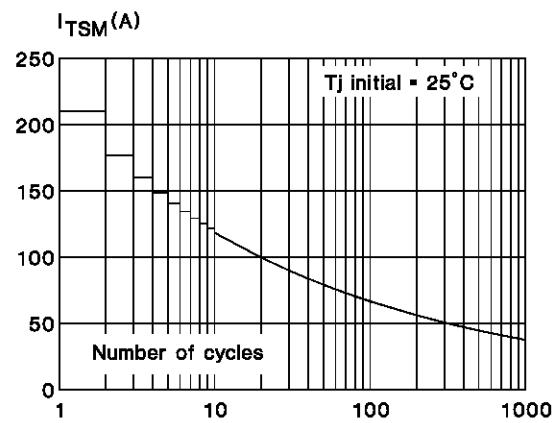
**Fig.5** : Relative variation of gate trigger current and holding current versus junction temperature.



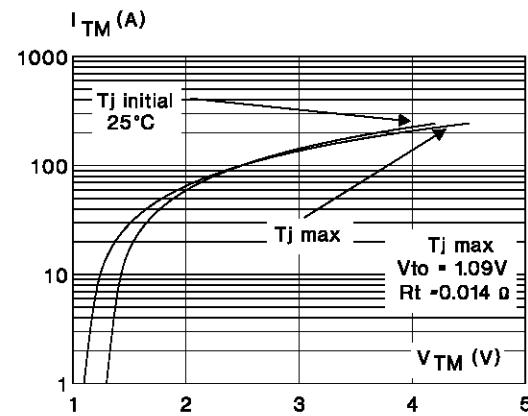
**Fig.7** : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .



**Fig.6** : Non Repetitive surge peak on-state current versus number of cycles.

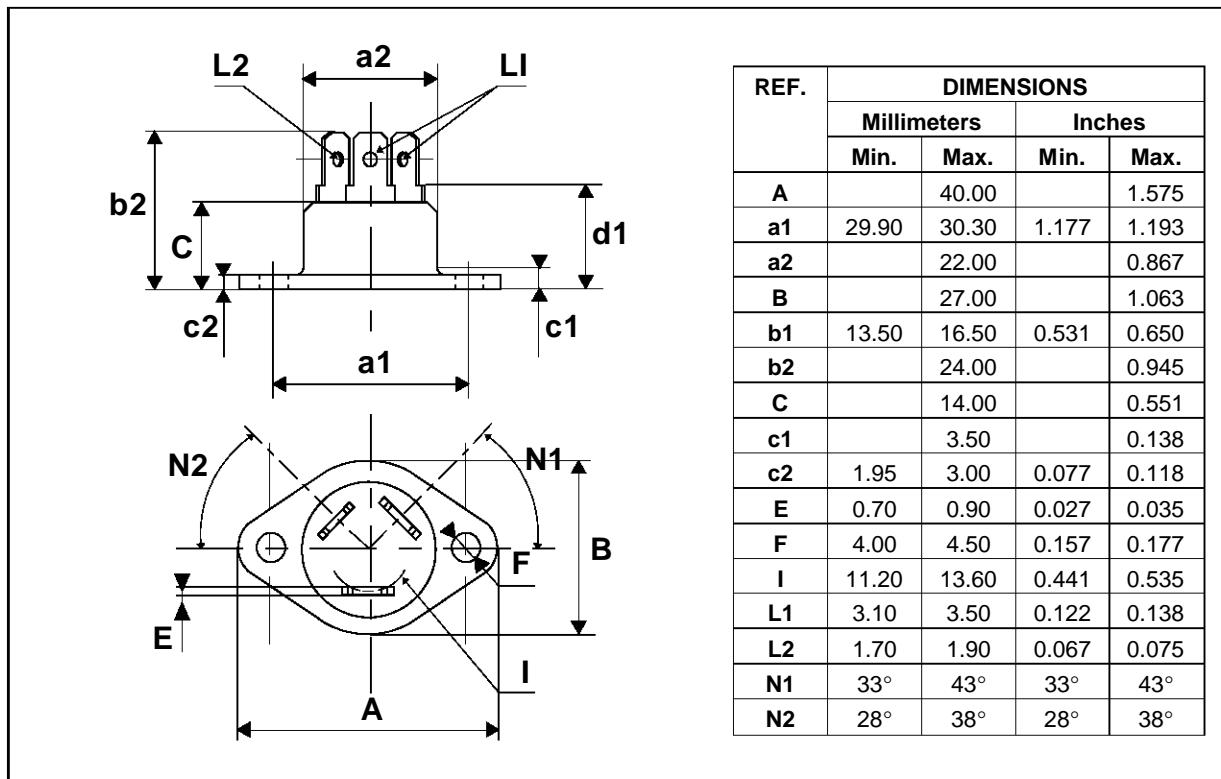


**Fig.8** : On-state characteristics (maximum values).



## PACKAGE MECHANICAL DATA

RD91 Plastic



Marking : type number

Weight : 20 g

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